



<b>Form 1449 (Rev. 10/01)</b>  <b>Information Disclosure Statement By Applicant</b>  (Use Several Sheets if Necessary)	Atty Docket No.	Application No.:
	NSC1P131X3/P04314P03	10/707,208
	Applicant:	
	Patwardhan et al.	
Filing Date	Group	
November 26, 2003	2814	

**U.S. Patent Documents**

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
WZ	A	6,288,444 B1	09/11/01	Abe et al.			06/04/99
	B						
	C						
	D						
	E						

**Foreign Patent or Published Foreign Patent Application**

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	F							
	G							
	H							

**Other Documents**

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
WZ	I	Kulicke & Soffa, "Flip Chip Products, Polymer Collar™ Wafer Level Package; Achieve Maximum Reliability for Wafer Level Packages!", December 7, 2001, pp. 1-2 <a href="http://www.kns.com">www.kns.com</a>
WZ	J	Kulicke & Soffa, "Flip Chip Division, Polymer Collar Wafer Level Package; See the Polymer Collar WLP difference!", December 7, 2001, pp. 1-2 <a href="http://www.kns.com">www.kns.com</a>
WZ	K	"Fundamentals of Microsystem Packaging", Rao R. Tummala, Chapters 2, 10, and 17, (May 8, 2001) McGraw-Hill Professional Publishing
WZ	L	"Chip Scale Package: Design, Materials, Process, Reliability, and Applications", John H. Lau and S.W. Ricky Lee, Chapter 1, Pages 1-41, (February 28, 1999) McGraw-Hill Professional Publishing
Examiner	V. K. Kulkarni	Date Considered 9/13/05

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.